



IEEE IES Students and Young Professionals Activity Committee (S&YP-AC)

How to apply for:

The IEEE IES S&YP Paper Assistance (IES-SYPA) at selected IEEE IES Conferences (ver20180127)

The IEEE IES *Web & Information Committee (WIC) with the Students and Young Professionals Activity Committee (S&YP-AC)* would like to introduce a draft of manual how to apply for the **IEEE IES S&YP Paper Assistance (IES-SYPA)** at selected IEEE IES Conferences.

The offer is focused, but not limited to the IEEE Students and Young Professionals (S&YP). Our support can indirectly help Supervisors, Mentors and Professors that would like to promote interesting work of their younger colleagues. Mentors can support their mentee not only by co-authoring scientific papers but also by advising them to join the IEEE IES to be able to attend the IEEE IES conferences.

1. The applications for the IES-SYPA are collected by the Manuscript Submission System (MSS) of the IEEE IES (Fig. 1) [1]. At least one co-Author should be IEEE, IES, Student or YP Member.

Manuscript Submission System Test Area

Submit a New Manuscript

NEW

Manuscript Number - not assigned yet

Please use **Access Existing Manuscript** for submitting a newer version of the same paper to ensure that the latest version is considered. In case of duplicate submissions only the first one will be considered, and all other will be removed before the review process starts.

Modify Existing Manuscript, Final Version, and Copyright Form Submission

TSD-

Manuscript Number Password

Please use this entrance to update existing manuscript, check review results, submit the final version, and sign the Web-based copyright form.

Lost Password Retrieval

Enter any author email here as filled in in the submission form. All authors are searched.

Advisory regarding plagiarism

"When does plagiarism occur? Is there an established percentage, a rule of thumb, a saturation point that we can use to determine when plagiarism has taken place? Or is it simply that 'plagiarism is plagiarism'? The answer may lie somewhere between the stark (and perhaps too simple) dictum and the convenience of ready-made measures. In most cases, the dictum can be applied appropriately: plagiarism is plagiarism. However, there are in fact degrees of plagiarism: one can steal an entire paper, or a section of a paper, or a page, a paragraph or a sentence. Even copying phrases without credit and quotation marks can be considered plagiarism. In other words, paraphrasing done improperly can qualify as plagiarism." - quoted from the IEEE Web site.

Read more at http://www.ieee.org/web/publications/rights/ID_Plagiarism.html.

Figure 1 The Manuscript Submission System (MSS) of the IEEE IES [1] (Attention: based on TEST example!).

2. During submission, the applicant should check the Student box in Fig.2. It should be noted that even the YP should check this box to see the application button in next section.
3. The Applicant for the IES-SYPA has to be the **IEEE IES Student and/or YP active member**. In this case, when conference registration and final version of the manuscript is submitted, the button for application shall be activated (Fig.2b).
4. The deadline for the IES-SYPA application is two weeks after paper acceptance announcement [2].
5. Applicants who are selected for the IEEE IES-SYPA should post their 3 minutes' video on the associated IEEE IES Facebook event page and the IEEE IES YouTube channel [3], [4].
6. The selected students of the IEEE IES-SYPA must follow the guidelines according to the video preparation and publications [5].
7. The selected students of the IEEE IES-SYPA must present the 3 minutes speech and the prepared video at the conference by themselves during the IEEE IES S&YPs 3 minutes session.

they will receive a copy of any automated email notification sent to you.

Title:	First M. Name:	Last Name:	Affiliation:	Affiliation Country:	e-mail:	Please retype e-mail:
Contact: *	Mrs. v	Maria	Skłodowska-Curie	saw University of Technology	Poland	mja@isep.pw.edu.pl

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Manuscript Information
This information will go to the conference program and the **Table of Contents of the printed proceedings exactly the way you type it** has to be in the manuscript. Please do double-check your spelling. For affiliation: do not use your title, use your company or university name and choose the country from the list.

Manuscript Title:

	Title:	First M. Name:	Last Name:	Affiliation:	Affiliation Country:	e-mail:	IEEE member	IES member	Student
1st Author: *	Mrs. v	Maria	Skłodowska-Curie	saw University of Technology	Poland	mja@isep.pw.edu.pl	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
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3rd Author:	Dr. v	Nikola	Tesla	Graz University of Technology	Austria	nikola@salnik.ac.au	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>

b) Then after the successfully reviews:

Figure 2 The possibility for the IES-SYPA application is available if an Author is the IEEE IES Student and/or YP active member. In this case, when conference registration and final version of the manuscript is submitted, the button for application shall be activated.

References:

- [1] <http://vps.ieee-ies.org/submit/>
- [2] <http://www.ieee-ies.org/students/travel>
- [3] <https://www.facebook.com/IndustrialElectronicsSociety/>
- [4] <https://www.youtube.com/channel/UCKg8GNii0Q-ieXE56AXosGg>
- [5] <http://www.ieee-ies.org/students/guidelines>

On behalf of the IEEE IES:
The VP-Membership Activities Yousef Ibrahim,
The VP-Conferences Activities Juan J. Rodriguez-Andina,
The President Xinghuo Yu, the President Elect Terry Martin, and Treasurer C.J. (Allen) Chen,

Sincerely yours,
The Chair of the WIC, Andres A. Nogueiras Melendez, and Aleksander Malinowski, and
Chair of the IEEE IES S&YP Committee
Marek Jasinski